

Title (en)  
Circuit board and method of manufacturing the same

Title (de)  
Leiterplatte und Verfahren zu deren Herstellung

Title (fr)  
Plaque à circuit et son procédé de fabrication

Publication  
**EP 0961533 B1 20060510 (EN)**

Application  
**EP 99108632 A 19990512**

Priority  
• JP 13173198 A 19980514  
• JP 15958698 A 19980608  
• JP 16814398 A 19980616

Abstract (en)  
[origin: EP0961533A2] Through holes (104) formed in an electrical insulating substrate (102) having adhesive layers (101) on its both surfaces are filled with a conductor (105). Then, supporting bases (106) having wiring layers (107) with a predetermined pattern are laminated on both the surfaces of the electrical insulating substrate (102), which are then heated and pressurized. After that, the supporting bases (106) are removed, thus obtaining a circuit board in which the wiring layers (107) have been embedded in the adhesive layers (101). The conductor (105) within the through holes (104) are compressed sufficiently, thus forming minute via holes with high reliability. <IMAGE>

IPC 8 full level  
**H01R 12/04** (2006.01); **H05K 3/20** (2006.01); **H05K 3/40** (2006.01); **H05K 3/46** (2006.01); **H05K 3/00** (2006.01); **H05K 3/38** (2006.01)

CPC (source: EP US)  
**H05K 3/20** (2013.01 - EP US); **H05K 3/205** (2013.01 - EP US); **H05K 3/4069** (2013.01 - EP US); **H05K 3/4614** (2013.01 - EP US); **H05K 3/4617** (2013.01 - EP US); **H05K 3/4658** (2013.01 - EP US); **H05K 3/007** (2013.01 - EP US); **H05K 3/386** (2013.01 - EP US); **H05K 3/4623** (2013.01 - EP US); **H05K 3/4688** (2013.01 - EP US); **H05K 2201/0116** (2013.01 - EP US); **H05K 2201/0195** (2013.01 - EP US); **H05K 2201/10378** (2013.01 - EP US); **H05K 2203/0152** (2013.01 - EP US); **H05K 2203/0384** (2013.01 - EP US); **H05K 2203/061** (2013.01 - EP US); **H05K 2203/1461** (2013.01 - EP US); **Y10S 428/901** (2013.01 - EP US); **Y10T 29/49126** (2015.01 - EP US); **Y10T 29/49155** (2015.01 - EP US); **Y10T 29/49165** (2015.01 - EP US); **Y10T 428/24917** (2015.01 - EP US); **Y10T 428/2804** (2015.01 - EP US)

Cited by  
EP1213952A3; EP1220586A3; EP1180920A3; EP1194020A3; US2014338192A1; US10178773B2; EP1791409A1; CN104538314A; US6576839B1; WO2008109412A1; WO0163989A1; US7321496B2; US7773386B2; US8188375B2; US8530752B2; US6799369B2; US6930395B2; US6459046B1; EP1180920A2; US6993836B2; US8114576B2; US8535797B2

Designated contracting state (EPC)  
DE FI FR GB SE

DOCDB simple family (publication)  
**EP 0961533 A2 19991201**; **EP 0961533 A3 20010411**; **EP 0961533 B1 20060510**; DE 69931212 D1 20060614; DE 69931212 T2 20070301; SG 86345 A1 20020219; TW 507508 B 20021021; US 6197407 B1 20010306; US 6532651 B1 20030318

DOCDB simple family (application)  
**EP 99108632 A 19990512**; DE 69931212 T 19990512; SG 1999001999 A 19990430; TW 88107133 A 19990503; US 30471499 A 19990504; US 50457000 A 20000215